SCBS2600 - JUNE 1993 - REVISED SEPTEMBER 2003

- Members of the Texas Instruments Widebus™ Family
- A-Port Outputs Have Equivalent 22-Ω
 Series Resistors, So No External Resistors
 Are Required
- Support Mixed-Mode Signal Operation (5-V Input and Output Voltages With 3.3-V V_{CC})
- Support Unregulated Battery Operation Down to 2.7 V
- Typical V_{OLP} (Output Ground Bounce)
 <0.8 V at V_{CC} = 3.3 V, T_A = 25°C
- I_{off} and Power-Up 3-State Support Hot Insertion
- Bus Hold on Data Inputs Eliminates the Need for External Pullup/Pulldown Resistors
- Distributed V_{CC} and GND Pins Minimize High-Speed Switching Noise
- Flow-Through Architecture Optimizes PCB Layout
- Latch-Up Performance Exceeds 500 mA Per JESD 17
- ESD Protection Exceeds JESD 22
 - 2000-V Human-Body Model (A114-A)
 - 200-V Machine Model (A115-A)
 - 1000-V Charged-Device Model (C101)

SN54LVTH162245 . . . WD PACKAGE SN74LVTH162245 . . . DGG OR DL PACKAGE (TOP VIEW)

| | | | | 1 |
|-----------------|----|--------|----|-------------------|
| 1DIR [| 1 | \cup | 48 | 1 <u>0E</u> |
| 1B1 [| 2 | | 47 |] 1A1 |
| 1B2 | 3 | | 46 |] 1A2 |
| GND [| 4 | | 45 | GND |
| 1B3 [| 5 | | |] 1A3 |
| 1B4 [| | | |] 1A4 |
| V _{CC} | | | |] v _{cc} |
| 1B5 | | | | 1A5 |
| 1B6 L | | | 40 |] 1A6 |
| GND [| 1 | | | GND |
| 1B7 | | | |] 1A7 |
| 1B8 | | | |] 1A8 |
| 2B1 | | | | 2A1 |
| 2B2 | | | | 2A2 |
| GND [| | | 34 | GND |
| 2B3 | 1 | | | 2A3 |
| 2B4 | | | 32 | 2A4 |
| V _{CC} | | | |] v _{cc} |
| 2B5 | | | | 2A5 |
| 2B6 | | | | 2A6 |
| GND [| | | | GND |
| 2B7 | | | | 2A7 |
| 2B8 | | | | 2 <u>A8</u> |
| 2DIR [| 24 | | 25 | 2 <mark>0E</mark> |
| | | | | , |

description/ordering information

The 'LVTH162245 devices are 16-bit (dual-octal) noninverting 3-state transceivers designed for low-voltage (3.3-V) V_{CC} operation, but with the capability to provide a TTL interface to a 5-V system environment.

ORDERING INFORMATION

| TA | PACKAGE [†] | | PACKAGET ORDERABLE PART NUMBER | | |
|----------------|-----------------------|-----------------------|--------------------------------|-------------------|--|
| | SSOP – DL | Tube SN74LVTH162245DL | | LVTH162245 | |
| | 330F - DL | Tape and reel | SN74LVTH162245DLR | LV 111102245 | |
| –40°C to 85°C | TSSOP – DGG | Tape and reel | SN74LVTH162245DGGR | LVTH162245 | |
| | VFBGA – GQL | Tape and reel | SN74LVTH162245KR | LL2245 | |
| | VFBGA – ZQL (Pb-free) | rape and reer | 74LVTH162245ZQLR | LL2245 | |
| -55°C to 125°C | CFP – WD | Tube | SNJ54LVTH162245WD | SNJ54LVTH162245WD | |

[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



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SCBS260O - JUNE 1993 - REVISED SEPTEMBER 2003

description/ordering information (continued)

These devices can be used as two 8-bit transceivers or one 16-bit transceiver. The devices allow data transmission from the A bus to the B bus or from the B bus to the A bus, depending on the logic level at the direction-control (DIR) input. The output-enable (\overline{OE}) input can be used to disable the device so that the buses are effectively isolated.

The A-port outputs, which are designed to source or sink up to 12 mA, include equivalent 22- Ω series resistors to reduce overshoot and undershoot.

Active bus-hold circuitry holds unused or undriven inputs at a valid logic state. Use of pullup or pulldown resistors with the bus-hold circuitry is not recommended.

When V_{CC} is between 0 and 1.5 V, the devices are in the high-impedance state during power up or power down. However, to ensure the high-impedance state above 1.5 V, \overline{OE} should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

These devices are fully specified for hot-insertion applications using I_{off} and power-up 3-state. The I_{off} circuitry disables the outputs, preventing damaging current backflow through the devices when they are powered down. The power-up 3-state circuitry places the outputs in the high-impedance state during power up and power down, which prevents driver conflict.

GQL OR ZQL PACKAGE (TOP VIEW)

2 3 4 5 6 000000 Α 000000 000000 С 000000 D \bigcirc ()()Е F \bigcirc \bigcirc 000000 G 000000 н 000000 J 000000

terminal assignments

| | 1 | 2 | 3 | 4 | 5 | 6 |
|---|------|-----|-----|-----|-----|-----|
| Α | 1DIR | NC | NC | NC | NC | 1OE |
| В | 1B2 | 1B1 | GND | GND | 1A1 | 1A2 |
| С | 1B4 | 1B3 | Vcc | Vcc | 1A3 | 1A4 |
| D | 1B6 | 1B5 | GND | GND | 1A5 | 1A6 |
| Е | 1B8 | 1B7 | | | 1A7 | 1A8 |
| F | 2B1 | 2B2 | | | 2A2 | 2A1 |
| G | 2B3 | 2B4 | GND | GND | 2A4 | 2A3 |
| Н | 2B5 | 2B6 | Vcc | Vcc | 2A6 | 2A5 |
| J | 2B7 | 2B8 | GND | GND | 2A8 | 2A7 |
| K | 2DIR | NC | NC | NC | NC | 2OE |

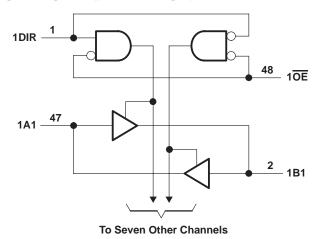
NC - No internal connection

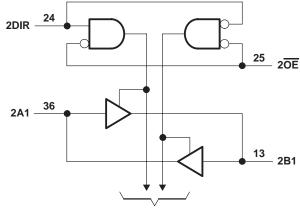
FUNCTION TABLE (each 8-bit section)

| INP | UTS | OPERATION | | | | |
|-----|-----|-----------------|--|--|--|--|
| OE | DIR | OPERATION | | | | |
| L | L | B data to A bus | | | | |
| L | Н | A data to B bus | | | | |
| Н | X | Isolation | | | | |



logic diagram (positive logic)





To Seven Other Channels

Pin numbers shown are for the DGG, DL, and WD packages.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

| Supply voltage range, V_CC—0.5 V to 4.6 V |
|--|
| Input voltage range, V _I (see Note 1) |
| Voltage range applied to any output in the high-impedance |
| or power-off state, V _O (see Note 1) |
| Voltage range applied to any output in the high state, V _O (see Note 1)0.5 V to V _{CC} + 0.5 V |
| Current into any output in the low state, IO: SN54LVTH162245 (B port) |
| SN74LVTH162245 (B port) |
| A port |
| Current into any output in the high state, IO (see Note 2): SN54LVTH162245 (B port) |
| SN74LVTH162245 (B port) 64 mA |
| A port |
| Input clamp current, I_{IK} ($V_I < 0$) |
| Output clamp current, I_{OK} ($V_O < 0$) |
| Package thermal impedance, θ_{JA} (see Note 3): DGG package |
| DL package |
| GQL/ZQL package |
| Storage temperature range, T _{stg} |

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.

- 2. This current flows only when the output is in the high state and $V_O > V_{CC}$.
- 3. The package thermal impedance is calculated in accordance with JESD 51-7.



SCBS260O - JUNE 1993 - REVISED SEPTEMBER 2003

recommended operating conditions (see Note 4)

| | | | | 162245 | SN74LVTH | UNIT | |
|---------------------|------------------------------------|-----------------|-----|--------|----------|------|------|
| | | | MIN | MAX | MIN | MAX | UNII |
| Vcc | Supply voltage | | 2.7 | 3.6 | 2.7 | 3.6 | V |
| VIH | High-level input voltage | | 2 | | 2 | | V |
| V _{IL} | Low-level input voltage | | | 0.8 | | 0.8 | V |
| VI | Input voltage | | | 5.5 | | 5.5 | V |
| lou | High level output ourrent | A port | | -12 | | -12 | mA |
| ЮН | High-level output current | B port | | -24 | | -32 | IIIA |
| lai | Low-level output current | A port | | 12 | | 12 | mA |
| IOL | Low-level output current | B port | | 48 | | 64 | IIIA |
| Δt/Δν | Input transition rise or fall rate | Outputs enabled | | 10 | | 10 | ns/V |
| Δt/ΔV _{CC} | Power-up ramp rate | · | 200 | | 200 | | μs/V |
| TA | Operating free-air temperature | | -55 | 125 | -40 | 85 | °C |

NOTE 4: All unused control inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.



SCBS260O - JUNE 1993 - REVISED SEPTEMBER 2003

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

| PARAMETER | | TEST COL | SN54L | SN54LVTH162245 | | | SN74LVTH162245 | | | | | |
|--------------------|------------------|--|---|----------------------|------------------|-------|----------------------|------------------|-------------|-------|--|--|
| PAR | AMETER | TEST COI | NDITIONS | MIN | TYP [†] | MAX | MIN | TYP [†] | MAX | UNIT | | |
| ٧ıK | | $V_{CC} = 2.7 \text{ V},$ | $I_{I} = -18 \text{ mA}$ | | | -1.2 | | | -1.2 | V | | |
| | A port | $V_{CC} = 2.7 \text{ V to } 3.6 \text{ V},$ | I _{OH} = -100 μA | V _{CC} -0.2 | | | V _{CC} -0.2 | | | | | |
| | A port | V _{CC} = 3 V, | $I_{OH} = -12 \text{ mA}$ | 2 | | | 2 | | | | | |
| V | | $V_{CC} = 2.7 \text{ V to } 3.6 \text{ V},$ | I _{OH} = -100 μA | V _{CC} -0.2 | | | V _{CC} -0.2 | | | V | | |
| VOH | D nort | $V_{CC} = 2.7 \text{ V},$ | $I_{OH} = -8 \text{ mA}$ | 2.4 | | | 2.4 | | | V | | |
| | B port | VCC = 3 V | I _{OH} = -24 mA 2 | | | | | | | | | |
| | | ACC = 2 A | $I_{OH} = -32 \text{ mA}$ | | | | 2 | | | | | |
| | A nort | $V_{CC} = 2.7 \text{ V to } 3.6 \text{ V},$ | I _{OL} = 100 μA | | | 0.2 | | | 0.2 | | | |
| | A port | V _{CC} = 3 V, | I _{OL} = 12 mA | | | 0.8 | | | 0.8 | | | |
| | | V27V | I _{OL} = 100 μA | | | 0.2 | | | 0.2 | | | |
| V/01 | | V _{CC} = 2.7 V | $I_{OL} = 24 \text{ mA}$ | | | 0.5 | | | 0.5 | V | | |
| VOL | D nort | | I _{OL} = 16 mA | | | 0.4 | | | 0.4 | V | | |
| | B port | V 2.V | I _{OL} = 32 mA | | | 0.5 | | | 0.5 | | | |
| | | VCC = 3 V | I _{OL} = 48 mA | | | 0.55 | | | | | | |
| | | | I _{OL} = 64 mA | | | | | | 0.55 | | | |
| | Control | V _{CC} = 3.6 V, | V _I = V _{CC} or GND | | | ±1 | | | ±1 | | | |
| | inputs | $V_{CC} = 0 \text{ or } 3.6 \text{ V},$ | V _I = 5.5 V | 10 | | | | | | | | |
| II | | | V _I = 5.5 V | | | 20 | | | 20 | 20 μΑ | | |
| | A or B ports‡ | V _{CC} = 3.6 V | $V_I = V_{CC}$ | | | 5 | | | 5 |] | | |
| | porto: | | V _I = 0 | | | -10 | | | -10 | | | |
| l _{off} | | $V_{CC} = 0$, | V_I or $V_O = 0$ to 4.5 V | | | | | | ±100 | μΑ | | |
| | | VCC = 3 V | V _I = 0.8 V | 75 | | | 75 | | | | | |
| litte e Lei | A or B ports | ACC = 2 A | V _I = 2 V | -75 | | | -75 | | | μΑ | | |
| I(hold) | A of B ports | V _{CC} = 3.6 V§, | V _I = 0 to 3.6 V | | | | | | 500 -750 | μΑ | | |
| lozpu | - | $\frac{V_{CC}}{OE} = 0$ to 1.5 V, $V_{O} = 0$ | 0.5 V to 3 V, | | | ±100* | | | ±100 | μΑ | | |
| I _{OZPD} | | $\frac{\text{V}_{CC}}{\text{OE}}$ = 1.5 V to 0, V_{O} = 0.5 V to 3 V, OE = don't care | | | | ±100* | | | ±100 | μΑ | | |
| | | V _{CC} = 3.6 V, | Outputs high | | | 0.19 | | | 0.19 | | | |
| ICC | | $I_{O} = 0$, Outputs low | | | - | 5 | | - | 5 | mA | | |
| | | $V_I = V_{CC}$ or GND | Outputs disabled | | - | 0.19 | | - | 0.19 | 0.19 | | |
| ΔI _{CC} ¶ | | $V_{CC} = 3 \text{ V to } 3.6 \text{ V}$, One input at $V_{CC} - 0.6 \text{ V}$, Other inputs at V_{CC} or GND | | | | 0.3 | | | 0.2 | mA | | |
| Ci | | V _I = 3 V or 0 | | | 4 | | | 4 | | pF | | |
| C _{io} | | V _O = 3 V or 0 | | | 10 | | | 10 | | pF | | |
| ² 10 | | 1 10 - 3 1 01 0 | | | 10 | | | 10 | | Рι | | |

^{*} On products compliant to MIL-PRF-38535, this parameter is not production tested.



[†] All typical values are at V_{CC} = 3.3 V, T_A = 25°C. † Unused pins at V_{CC} or GND. § This is the bus-hold maximum dynamic current. It is the minimum overdrive current required to switch the input from one state to another.

This is the increase in supply current for each input that is at the specified TTL voltage level, rather than VCC or GND.

SCBS260O - JUNE 1993 - REVISED SEPTEMBER 2003

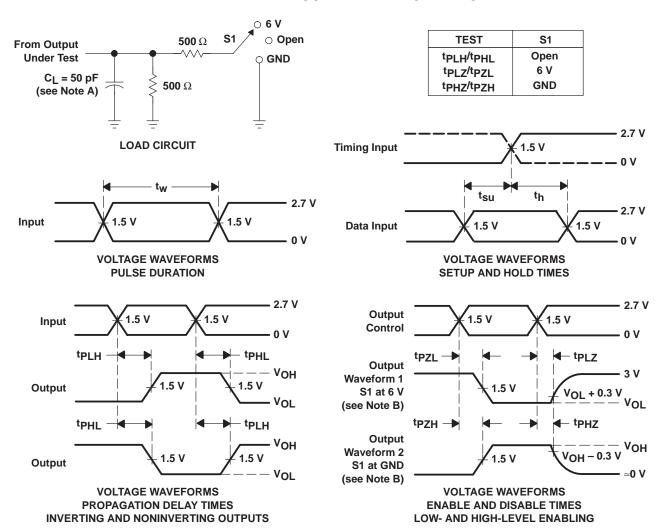
switching characteristics over recommended operating free-air temperature range, C_L = 50 pF (unless otherwise noted) (see Figure 1)

| | | | | N54LVT | H162245 | 5 | SN74LVTH162245 | | | | | |
|------------------|-----------------|----------------|------------------------------------|--------|-------------------------|-----|------------------------------------|------------------|-----|-------------------------|-----|------|
| PARAMETER | FROM (INPUT) | TO (OUTPUT) | V _{CC} = 3.3 V ± 0.3 V | | V _{CC} = 2.7 V | | V _{CC} = 3.3 V ± 0.3 V | | V | V _{CC} = 2.7 V | | UNIT |
| | | | MIN | MAX | MIN | MAX | MIN | TYP [†] | MAX | MIN | MAX | |
| t _{PLH} | А | В | 1 | 3.5 | | 4 | 1 | 2.3 | 3.3 | | 3.7 | ns |
| t _{PHL} | A | В | 1 | 3.5 | | 3.9 | 1 | 2.2 | 3.3 | | 3.5 | 115 |
| t _{PLH} | В | А | 1 | 4.3 | | 5.3 | 1 | 2.8 | 4 | | 4.6 | ns |
| t _{PHL} | Ь | A | 1 | 4.2 | | 4.5 | 1 | 2.5 | 3.4 | | 3.6 | 115 |
| ^t PZH | ŌĒ | В | 1 | 4.8 | | 5.9 | 1 | 2.8 | 4.6 | | 5.4 | ns |
| t _{PZL} | OE | В | 1 | 4.8 | | 5.5 | 1 | 3 | 4.6 | | 5.2 | 115 |
| ^t PZH | ŌE | А | 1 | 5.5 | | 7.2 | 1 | 3.3 | 5.3 | | 6.3 | ns |
| t _{PZL} | OE | ^ | 1 | 5.4 | | 6.4 | 1 | 3.3 | 5.1 | | 5.8 | 115 |
| ^t PHZ | ŌĒ | В | 1.5 | 5.5 | | 5.8 | 1.5 | 3.8 | 5.2 | | 5.5 | ns |
| t _{PLZ} | OE | В | 1.5 | 5.5 | | 5.8 | 1.5 | 3.5 | 5.1 | | 5.4 | 115 |
| ^t PHZ | ŌĒ | А | 1.5 | 5.8 | | 6.5 | 1.5 | 4 | 5.6 | | 5.9 | ns |
| ^t PLZ | OE | ^ | 1.2 | 6.3 | | 6.3 | 1.5 | 3.8 | 5.5 | | 5.5 | 115 |
| tsk(o) | | | | | | | | | 0.5 | | | ns |

 $^{^{\}dagger}$ All typical values are at VCC = 3.3 V, TA = 25°C.



PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_L includes probe and jig capacitance.

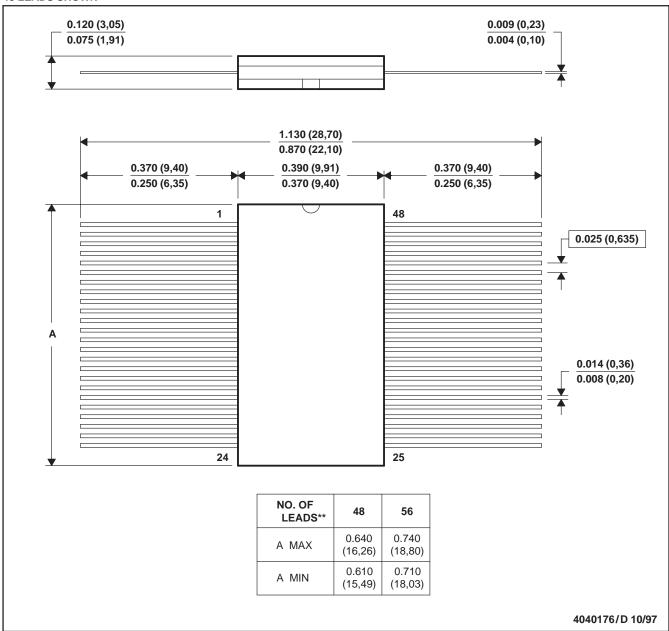
- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, Z_{O} = 50 Ω , $t_{f} \leq$ 2.5 ns, $t_{f} \leq$ 2.5 ns.
- D. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

WD (R-GDFP-F**)

CERAMIC DUAL FLATPACK

48 LEADS SHOWN



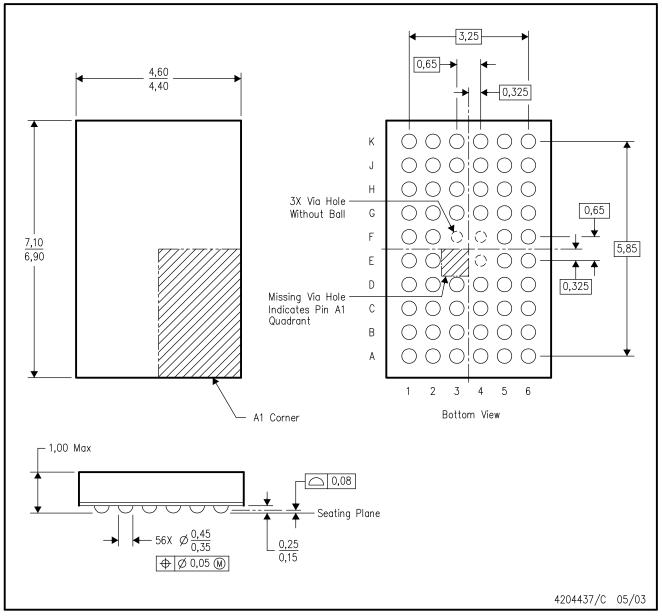
NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only
- E. Falls within MIL STD 1835: GDFP1-F48 and JEDEC MO-146AA GDFP1-F56 and JEDEC MO-146AB



ZQL (R-PBGA-N56)

PLASTIC BALL GRID ARRAY



NOTES:

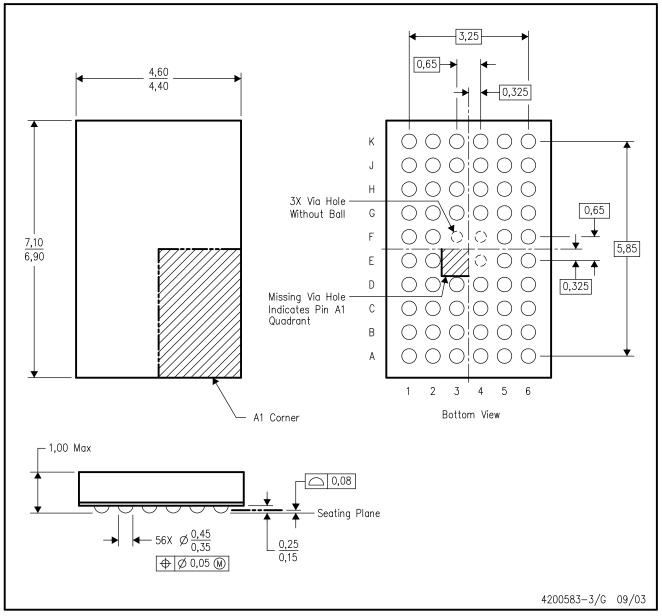
- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. MicroStar Junior™ BGA configuration.
- D. Falls within JEDEC MO-225 variation BA.
- E. This package is lead—free. Refer to the 56 GQL package (drawing 4200583) for tin—lead (SnPb).

MicroStar Junior is a trademark of Texas Instruments.



GQL (R-PBGA-N56)

PLASTIC BALL GRID ARRAY



NOTES:

- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. MicroStar Junior™ BGA configuration.
- D. Falls within JEDEC MO-225 variation BA.
- E. This package is tin-lead (SnPb). Refer to the 56 ZQL package (drawing 4204437) for lead-free.

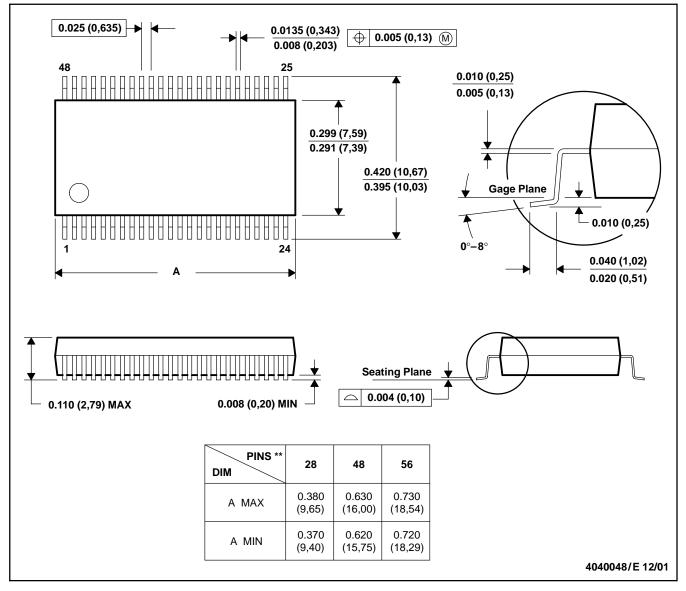
MicroStar Junior is a trademark of Texas Instruments.



DL (R-PDSO-G**)

48 PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

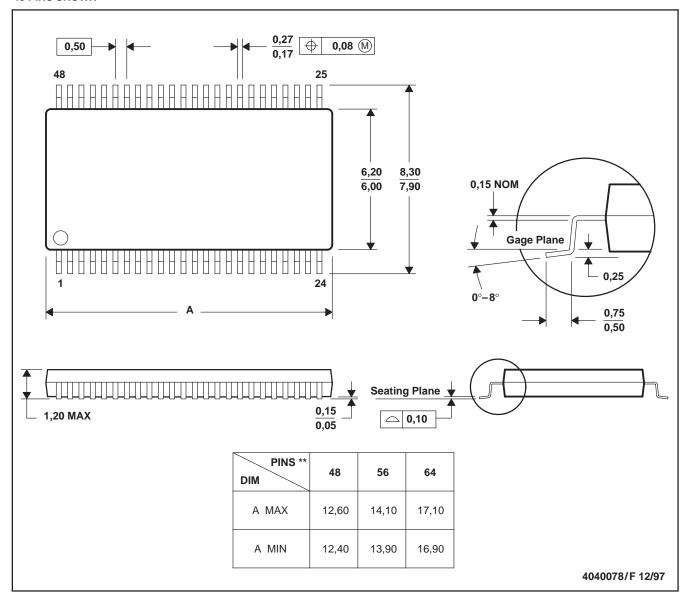
C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).

D. Falls within JEDEC MO-118

DGG (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

48 PINS SHOWN



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold protrusion not to exceed 0,15.

D. Falls within JEDEC MO-153

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